



V_Z : 2.0 - 100 Volts
P_D : 500 mWatts

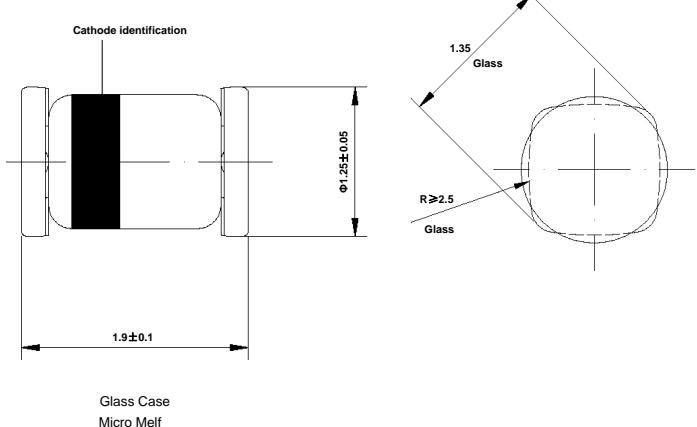
MICRO MELF

Features

1. Saving space
2. Fits onto SOD 323/SOT 23 footprints
3. Micro Melf package

Applications

Voltage stabilization



Absolute Maximum Ratings

T_j=25°C

Parameter	Test Conditions	Type	Symbol	Value	Unit
Power dissipation	R _{thJA} ≤ 300K/W		P _V	500	mW
Z-current			I _Z	P _V /V _Z	mA
Junction temperature			T _j	175	°C
Storage temperature range			T _{stg}	-65~+175	°C

Maximum Thermal Resistance

T_j=25°C

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mm×50mm×1.6mm	R _{thJA}	500	K/W

Stresses exceeding maximum ratings may damage the device. Maximum ratings are stress ratings only. Functional operation above the recommended operating conditions is not implied. Extended exposure to stresses above the recommended operating conditions may affect device reliability.

Electrical Characteristics

T_j=25°C

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	I _F =200mA		V _F			1.5	V



Type	V _{znom}	I _{zT} for V _{zT} and	r _{zT}	r _{zK} at	I _{zK}	I _R and	I _R at	V _R	T K _{vz}	
BZM55B.	V	mA	V	Ω	Ω	mA	μA	μA ₁₎	V	%/K
2V0	2.0	5	1.96~2.04	100	<600	1	<150	<300	1	-0.09~-0.06
2V2	2.2	5	2.16~2.24	100	<600	1	<150	<300	1	-0.09~-0.06
2V4	2.4	5	2.35~2.45	<85	<600	1	<50	<100	1	-0.09~-0.06
2V7	2.7	5	2.64~2.76	<85	<600	1	<10	<50	1	-0.09~-0.06
3V0	3.0	5	2.94~3.06	<85	<600	1	<4	<40	1	-0.08~-0.05
3V3	3.3	5	3.24~3.36	<85	<600	1	<2	<40	1	-0.08~-0.05
3V6	3.6	5	3.52~3.36	<85	<600	1	<2	<40	1	-0.08~-0.05
3V9	3.9	5	3.82~3.98	<85	<600	1	<2	<40	1	-0.08~-0.05
4V3	4.3	5	4.22~4.38	<75	<600	1	<1	<20	1	-0.06~-0.03
4V7	4.7	5	4.60~4.80	<60	<600	1	<0.5	<10	1	-0.05~+0.02
5V1	5.1	5	5.00~5.20	<35	<550	1	<0.1	<2	1	-0.02~+0.02
5V6	5.6	5	5.48~5.72	<25	<450	1	<0.1	<2	1	-0.05~+0.05
6V2	6.2	5	6.08~6.32	<10	<200	1	<0.1	<2	2	0.03~0.06
6V8	6.8	5	6.66~6.94	<8	<150	1	<0.1	<2	3	0.03~0.07
7V5	7.5	5	7.35~7.65	<7	<50	1	<0.1	<2	5	0.03~0.07
8V2	8.2	5	8.04~8.36	<7	<50	1	<0.1	<2	6.2	0.03~0.08
9V1	9.1	5	8.92~9.28	<10	<50	1	<0.1	<2	6.8	0.03~0.09
10	10	5	9.80~10.20	<15	<70	1	<0.1	<2	7.5	0.03~0.1
11	11	5	10.78~11.22	<20	<70	1	<0.1	<2	8.2	0.03~0.11
12	12	5	11.76~12.24	<20	<90	1	<0.1	<2	9.1	0.03~0.11
13	13	5	12.74~13.26	<26	<110	1	<0.1	<2	10	0.03~0.11
15	15	5	14.70~15.30	<30	<110	1	<0.1	<2	11	0.03~0.11
16	16	5	15.70~16.30	<40	<170	1	<0.1	<2	12	0.03~0.11
18	18	5	17.64~18.36	<50	<170	1	<0.1	<2	13	0.03~0.11
20	20	5	19.60~20.40	<55	<220	1	<0.1	<2	15	0.03~0.11
22	22	5	21.55~22.45	<55	<220	1	<0.1	<2	16	0.04~0.12
24	24	5	23.5~24.5	<80	<220	1	<0.1	<2	18	0.04~0.12
27	27	5	26.4~27.6	<80	<220	1	<0.1	<2	20	0.04~0.12
30	30	5	29.4~30.6	<80	<220	1	<0.1	<2	22	0.04~0.12
33	33	5	32.4~33.6	<80	<220	1	<0.1	<2	24	0.04~0.12
36	36	5	35.3~36.7	<80	<220	1	<0.1	<2	27	0.04~0.12
39	39	2.5	38.2~39.8	<90	<500	0.5	<0.1	<5	30	0.04~0.12
43	43	2.5	42.1~43.9	<90	<600	0.5	<0.1	<5	33	0.04~0.12
47	47	2.5	46.1~47.9	<110	<700	0.5	<0.1	<5	36	0.04~0.12
51	51	2.5	50.0~52.0	<125	<700	0.5	<0.1	<10	39	0.04~0.12
56	56	2.5	54.9~57.1	<135	<1000	0.5	<0.1	<10	43	0.04~0.12
62	62	2.5	60.8~63.2	<150	<1000	0.5	<0.1	<10	47	0.04~0.12
68	68	2.5	66.6~69.4	<200	<1000	0.5	<0.1	<10	51	0.04~0.12
75	75	2.5	73.5~76.5	<250	<1500	0.5	<0.1	<10	56	0.04~0.12
82	82	2.5	80.4~83.6	<300	<2000	0.5	<0.1	<10	62	0.04~0.12
91	91	1.0	89.2~92.8	<450	<5000	0.1	<0.1	<10	68	0.04~0.12
100	100	1.0	98~102	<450	<5000	0.1	<0.1	<10	75	0.04~0.12

¹⁾ at T_j=150°C



Characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified)

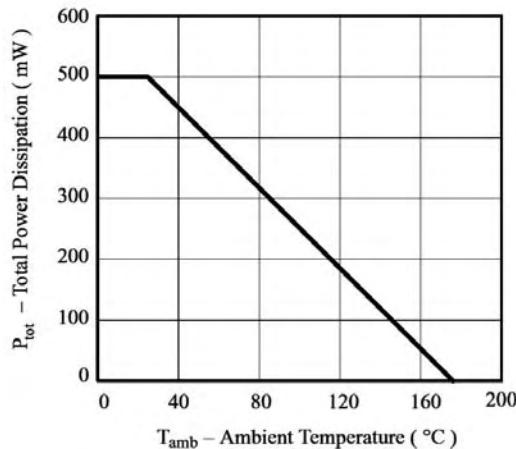


Figure 1. Total Power Dissipation vs. Ambient Temperature

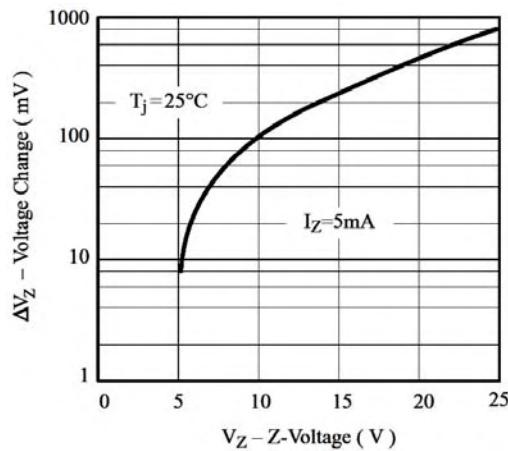


Figure 2. Typical Change of Working Voltage under Operating Conditions at $T_{\text{amb}}=25^\circ\text{C}$

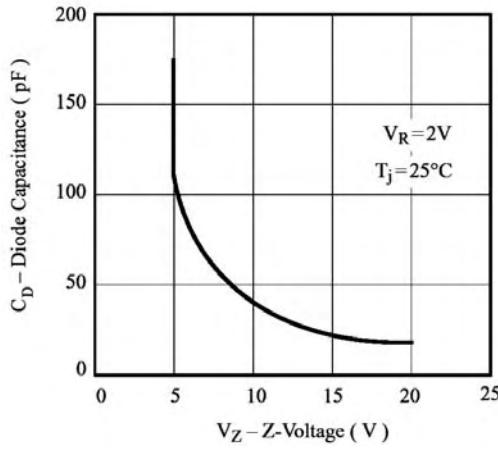


Figure 3. Diode Capacitance vs. Z-voltage

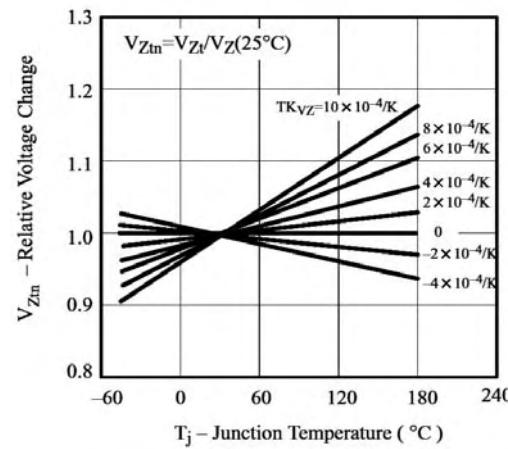


Figure 4. Typical Change of Working Voltage Vs. Junction Temperature

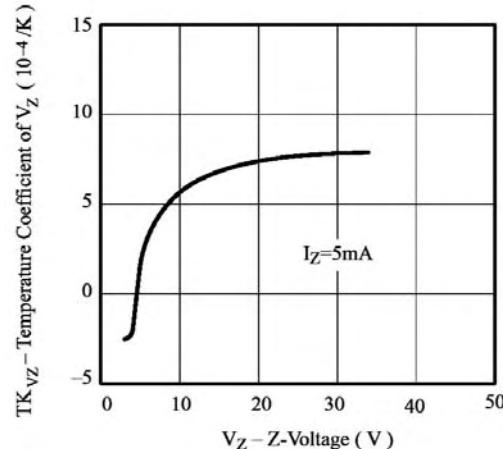


Figure 5. Temperature Coefficient of V_z vs. Z-Voltage

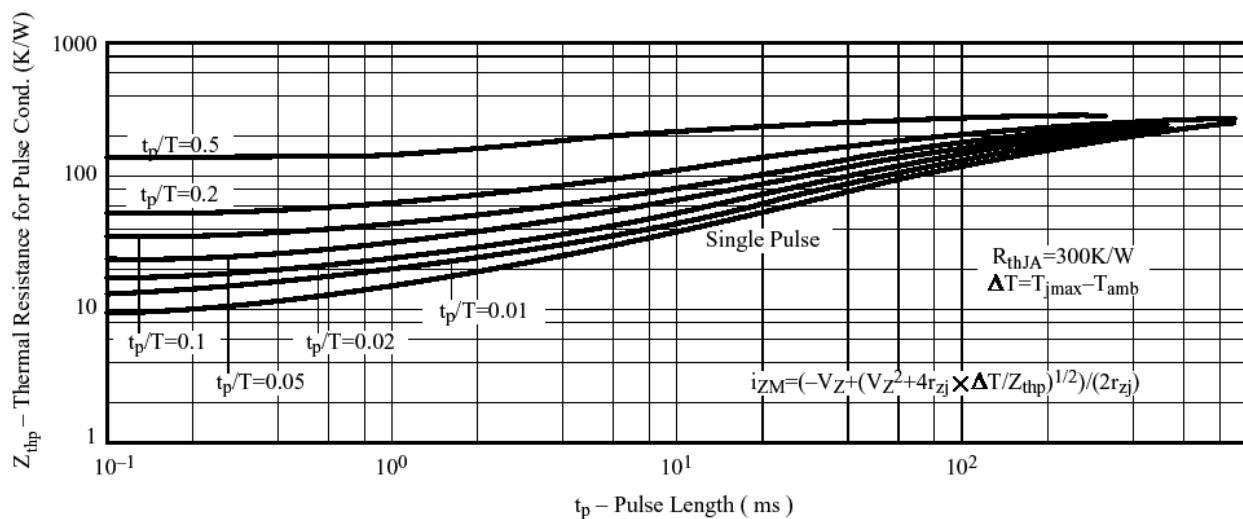
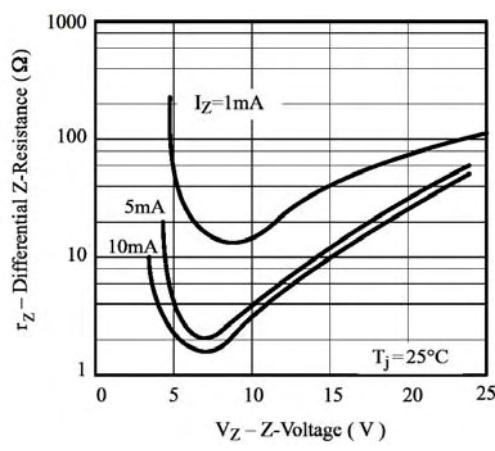
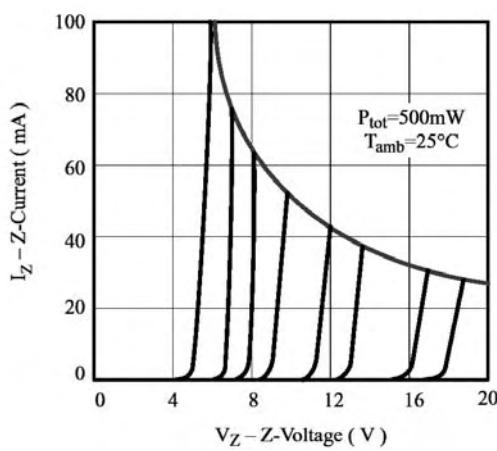
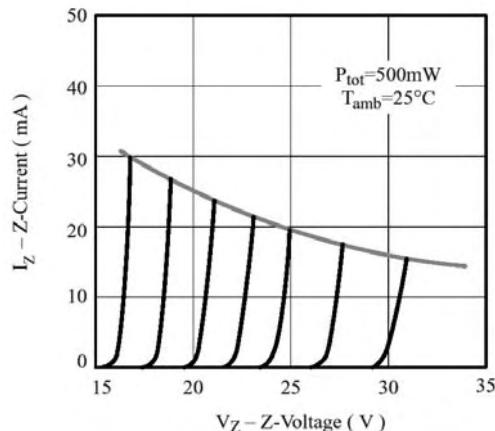
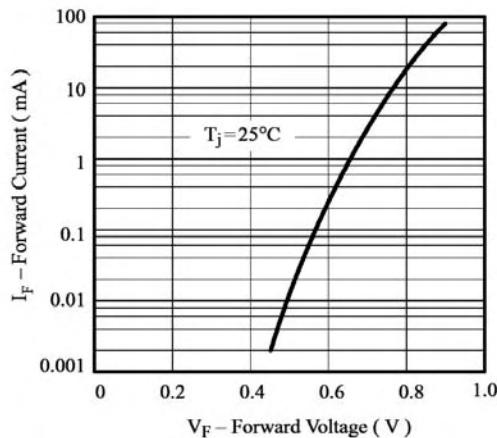


Figure 10. Thermal Response